Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	1998kr-0003970.ap,prai.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/01/13 14:56
L2	30	((wafer dic$6 protective) adj tape) same (release adj tape)	US-PGPUB; USPAT	OR	ON	2005/01/13 14:59
L3	3	((wafer dic$6 protective) adj tape) and (release adj tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 15:01
L4	2	jp-2003209073-$.did.	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 15:02
L5	50	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and (dbg (dic$6 near2 grind$6))	US-PGPUB; USPAT	OR	ON	2005/01/13 15:04
L7	6	"6297131".URPN.	USPAT	OR	OFF	2005/01/13 15:35
L8	117	((dbg (dic$6 near2 grind$6))) and (semiconductor wafer package chip ic integrated die dice silicon tape)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/13 15:40
L9	146	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((wafer dic$6 protect$6 releas$6) adj tape)) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe$8))	US-PGPUB; USPAT	OR	ON	2005/01/13 15:48
L10	40	"5480842".URPN.	USPAT	OR	OFF	2005/01/13 16:00
L11	7	((wafer dic$6 protect$6 releas$6) adj tape) same (((die chip) adj pad) with (leadframe (lead adj frame) ((((package wiring) adj substrate) carrier) with (solder adj ball))))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:01
L12	0	((wafer dic$6 protect$6 releas$6) adj tape) same ((die chip) adj pad) same (leadframe (lead adj frame)) same ((((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:03

L13	2	((die chip) adj pad) same (leadframe (lead adj frame)) same ((((package wiring) adj substrate) carrier module) with (solder adj ball))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:03
L14	0	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protective adj tape) with (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:04
L15	1	((protective adj tape) same (thermal adj degradation))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:05
L16	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect$6 adj tape) with adhe$8 with (weaken degrad$8) with heat$6)	US-PGPUB; USPAT	OR	ON	2005/01/13 16:06
L17	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect$6 adj tape) same adhe$8 same (weaken degrad$8) same heat$6)	US-PGPUB; USPAT	OR	ON	2005/01/13 16:07
L18	1	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect$6 adj tape) same (adhe$8 bond$6) same (weaken degrad$8) same (heat$6 thermal$4 temperature))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:07
L19	17	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584. ccls.) and ((protect$6 adj tape) same (adhe$8 bond$6) same (heat$6 thermal$4 temperature))	US-PGPUB; USPAT	OR	ON	2005/01/13 16:08